

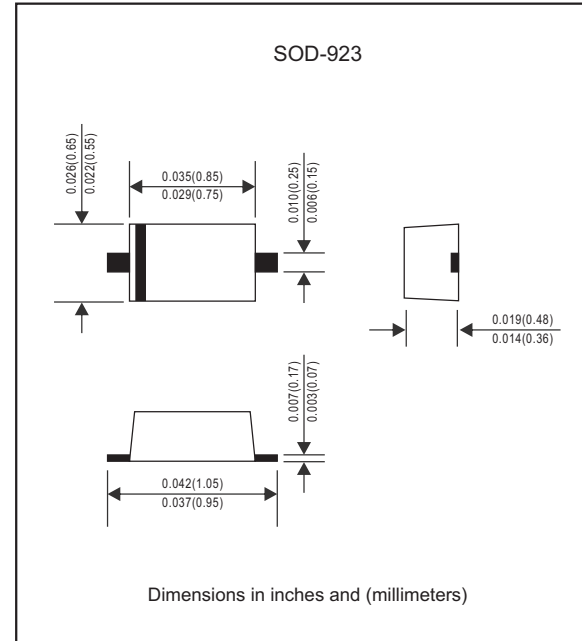
Features

- Silicon Epitaxial Planer
- Low Forward Voltage and Low Reverse Current
- High Reliability
- Schottky Barrier Diodes Encapsulated in a SOD-923 Package
- Lead-free parts meet RoHS requirements.
- Compliant to Halogen-free

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-923
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
DC Reverse Voltage		V_R	30			V
Mean rectifying current		I_O			100	mA
Forward surge current	60Hz for 1 cycle	I_{FSM}			500	mA
Thermal Resistance	Junction to Ambient	$R_{\theta JA}$		520		$^\circ\text{C/W}$
Power Dissipation		P_D			150	mW
Operating junction temperature range		T_J	-55		+125	$^\circ\text{C}$
Storage temperature range		T_{STG}	-55		+125	$^\circ\text{C}$

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 10 \text{ mA}$	V_F		0.28	0.35	V
	$I_F = 20 \text{ mA}$	V_F		0.32	0.42	V
Reverse current	$V_R = 10 \text{ V}$	I_R			10	μA

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CHARACTERISTICS

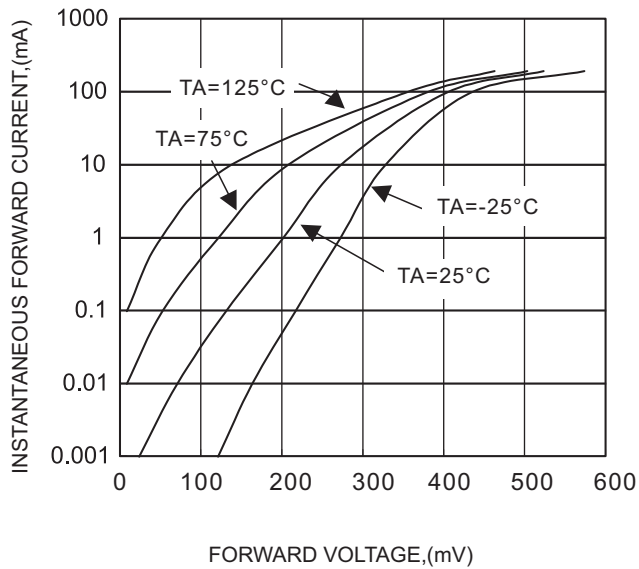


FIG.2 - TYPICAL REVERSE CHARACTERISTICS

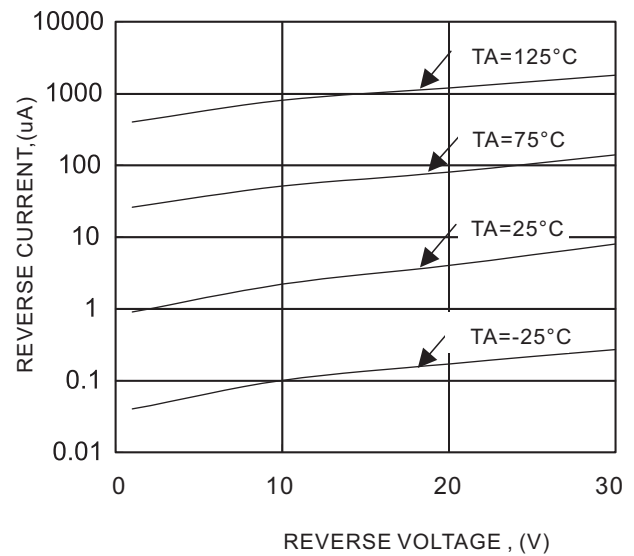
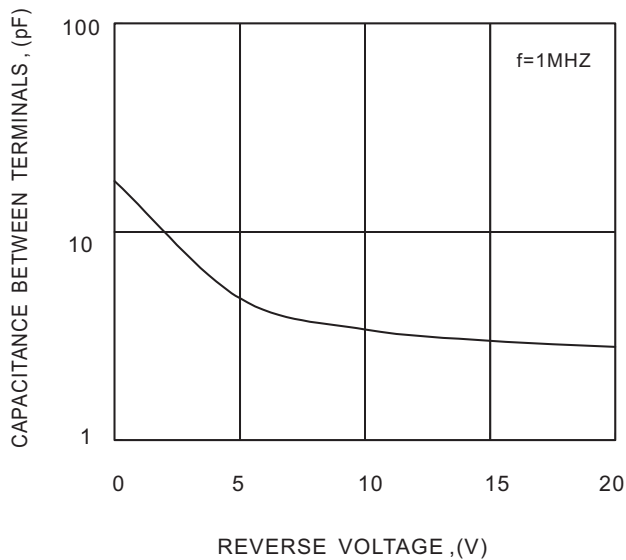


FIG.3-TYPICAL TERMINALS CAPACITANCE



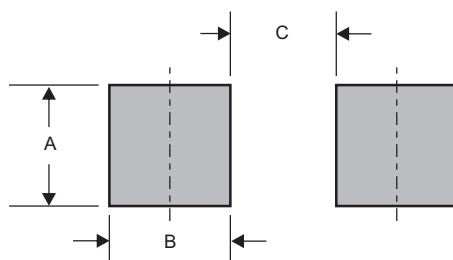
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
1SS416	F

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-923	0.016 (0.40)	0.012 (0.30)	0.024 (0.60)